

REMARKS

Claims 1–6 are pending. Claims 3-5 were withdrawn from consideration.

In this Office Action, Claims 1, 2, and 6 were rejected under 35 U.S.C. §103(a) as being unpatentable over JP 2001-93795 (“JP ‘795”) in view of Hisai et al. (U.S. 2003/192,686); and also were rejected under 35 U.S.C. §103(a) over JP 2003-53741 (“JP ‘741”) in view of Hisai et al. Claim 2 was rejected under 35 U.S.C. §103(a) as allegedly being unpatentable over any of the prior art as applied to Claims 1, 2 and 6 above and further in view of JP 4-338242 (“JP ‘242”). Withdrawal of these rejections are respectfully requested in view of the above amendments and the following remarks.

The present invention is directed to a cooling apparatus for a wafer baking plate for achieving a uniform temperature distribution and remarkably reducing cooling time, thereby increasing wafer product yield. Specifically, a hollow bore is formed in the heat transfer plate of the wafer baking plate and is partially filled with a liquid working fluid. A cooling pipe is laid along the hollow bore in the heat transfer plate, for circulating a cooling medium.

As indicated above, the Examiner has rejected Claims 1, 2 and 6 rejected under 35 U.S.C. §103(a) as allegedly being unpatentable over JP ‘795 in view of Hisai et al. More specifically, the Examiner asserts that JP ‘795 teaches all the claimed features, except for a cooling pipe in the cavity 515, which the Examiner asserts is taught in Hisai et al. Claim 1 has been amended to further recite the cooling pipe as “along the hollow bore”, which is supported in Figs. 2 and 3.

The Examiner states that Hisai et al. teaches in the type of working fluid heater disclosed by JP ‘795, a cooled pipe 22 is located in the sealed chamber containing the washing fluid. However, amended Claim 1 of the present invention discloses a cooling pipe laid along the hollow bore in the heat transfer plate. In contrast to amended Claim 1,

the cooled pipe 22 in Hisai et al. is located merely in the inner space 12 in the holding table 11 (see [0057] and Fig. 3). As such, Hisai et al. does not cure the deficiencies of JP '795. This is a clear distinction between the present invention and the cited references. Accordingly, it is respectfully requested that the rejections of Claims 1, 2 and 6 be withdrawn.

Regarding the §103(a) rejection of Claims 1, 2 and 6 over JP '741 in view of Hisai et al., similar arguments apply to distinguish the cooling apparatus of amended Claim 1 from JP '741 in view of Hisai et al. as were used above to distinguish the apparatus of amended Claim 1 from JP '795 in view of Hisai et al.

JP '741 does not disclose or suggest a hollow bore formed in the heat transfer plate and partially filled with a liquid working fluid, and a cooling pipe laid along the hollow bore in the heat transfer plate.

Accordingly, it is respectfully submitted that all of the pending claims are in condition for allowance.

Should the Examiner believe that a telephone conference or personal interview would facilitate resolution of any matters, the Examiner may contact Applicants' attorney at the number given below.

Respectfully submitted,



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